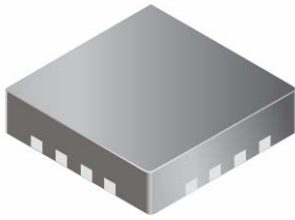


MLP/QFN -16 Package:



All dimensions reference only, not for tooling use
 (reference JEDEC MO-220WEED-4)
 Dimensions in millimeters
 U.S. Customary dimensions (in.) in brackets, for reference only
 Dimensions exclusive of mold flash, gate burrs, and dambar protrusions
 Exact case and lead configuration at supplier discretion within limits shown

- Terminal #1 mark area
- Exposed thermal pad (reference only, terminal #1 identifier appearance at supplier discretion)
- Reference land pattern layout (reference IPC7351 QFN50P300X300X80-17W4M); adjust as necessary to meet application process requirements and PCB layout tolerances; when mounting on a multilayer PCB, thermal vias at the exposed thermal pad land can improve thermal dissipation (reference EIA/JEDEC Standard JESD51-5)

